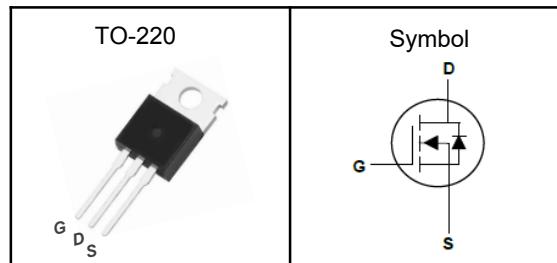


650V Super Junction Power MOSFET

Features

- Low drain-source on-resistance: $R_{DS(ON)}=0.55\Omega(\text{typ})$
- Easy to control gate switching
- Enhancement mode: $V_{th} = 2$ to $4V$
- 100% avalanche tested
- RoHS compliant

Pin Description



Applications

- Switch Mode Power Supply (SMPS)
- TV power & LED Lighting Power
- AC to DC Converters
- Telecom

V_{DSS}	650	V
$R_{DS(ON)-\text{Typ}}$	550	$\text{m}\Omega$
I_D	8	A

Absolute Maximum Ratings ($T_J=25^\circ\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
V_{DSS}	Drain-Source Voltage	650	V
V_{GSS}	Gate-Source Voltage	± 30	V
T_J	Maximum Junction Temperature	-55 to 150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
E_{AS}	Single Pulse Avalanche Energy ^③	106	mJ
$I_{DM}^{①}$	300 μs Pulse Drain Current Tested	31.2	A
I_D	Continuous Drain Current	8	A
P_D	Maximum Power Dissipation	80	W
I_{AS}	Avalanche Current	2.7	A
dv/dt	MOSFET dv/dt ruggedness, $V_{DS} = 0 \dots 400V$	50	V/ns
	Reverse diode dv/dt ^③ $V_{DS}=0 \dots 400V$, $I_{SD} \leq I_D$	15	

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	62	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case ₁	1.55	$^\circ\text{C}/\text{W}$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C .

Note ③ : Surface Mounted on 1in² FR-4 board with 1oz.



FS65R650CE

650V Super Junction Power MOSFET

Electrical Characteristics ($T_J=25^\circ\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	650	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=650\text{V}$, $V_{\text{GS}}=0\text{V}$	---	---	1	μA
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_D=250\mu\text{A}$	2.0	---	4.0	V
I_{GSS}	Gate Leakage Current	$V_{\text{GS}}=\pm 30\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
$R_{\text{DS}(\text{ON})}$	Drain-Source On-state Resistance	$V_{\text{GS}}=10\text{V}$, $I_D=3.5\text{A}$	---	550	650	$\text{m}\Omega$
Dynamic Characteristics^⑤						
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=100\text{V}$, Freq.=1.0MHz	---	480	---	pF
C_{oss}	Output Capacitance		---	22	---	
C_{rss}	Reverse Transfer Capacitance		---	1.1	---	
$T_{\text{d}(\text{on})}$	Turn-on Delay Time	$V_{\text{GS}}=10\text{V}$, $V_{\text{DD}}=400\text{V}$, $I_D=3.9\text{A}$, $R_G=10\Omega$	---	11	---	nS
T_r	Turn-on Rise Time		---	21	---	
$T_{\text{d}(\text{off})}$	Turn-off Delay Time		---	40	---	
T_f	Turn-off Fall Time		---	31	---	
Q_g	Total Gate Charge	$V_{\text{GS}}=10\text{V}$, $V_{\text{DD}}=400\text{V}$, $I_b=7.8\text{A}$	---	14	---	nC
Q_{gs}	Gate-Source Charge		---	3.2	---	
Q_{gd}	Gate-Drain Charge		---	5.6	---	
R_g	Gate resistance	$f=1\text{ MHz}$, open drain	---	9.6	---	Ω
Source-Drain Characteristics						
I_s	Continuous Source Current		---	---	7.8	A
ISM	Maximum Pulsed Drain-Source Diode Forward Current		---	---	31.2	A
V_{SD}	Diode Forward Voltage	$I_s=7.8\text{A}$, $V_{\text{GS}}=0\text{V}$	---	---	1.4	V
t_{rr}	Reverse recovery time	$I_s=3.9\text{A}$, $V_{\text{GS}}=0\text{V}$ $dI/dt=100\text{A}/\mu\text{s}$	---	205	---	ns
Q_{rr}	Reverse recovery charge		---	1.4	---	nC
I_{rrm}	Peak Reverse Recovery Current		---	12	---	A

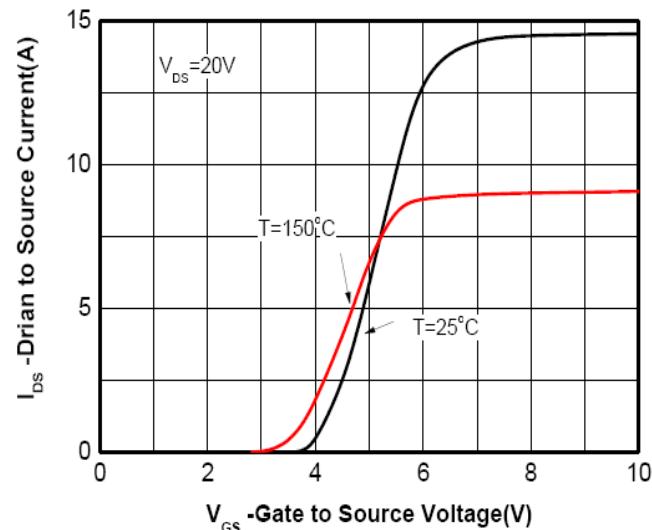
Note ④: Pulse test (pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$).

Note ⑤: Guaranteed by design, not subject to production testing.

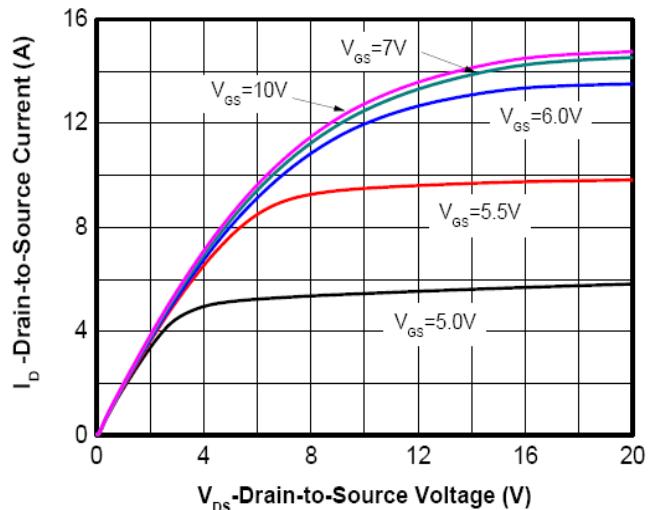
650V Super Junction Power MOSFET

Typical Characteristics

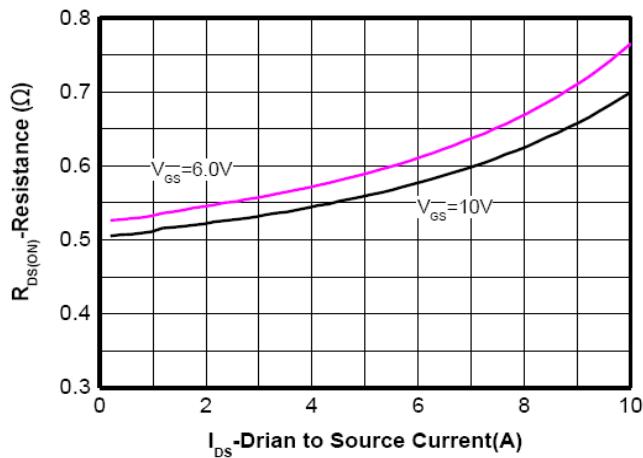
Typ. transfer characteristics



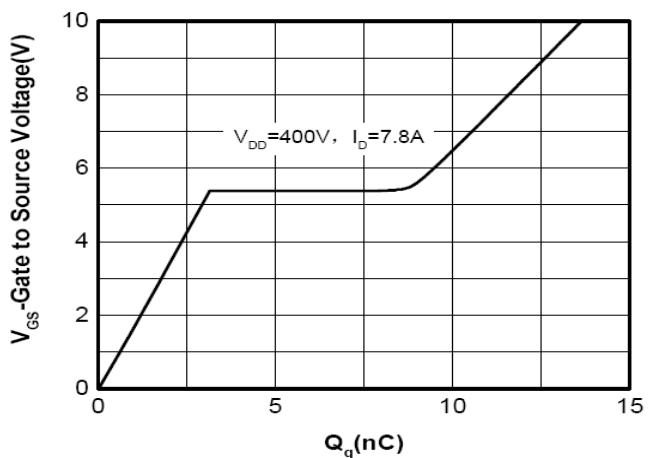
Typ. output characteristics $T_J=25^\circ\text{C}$



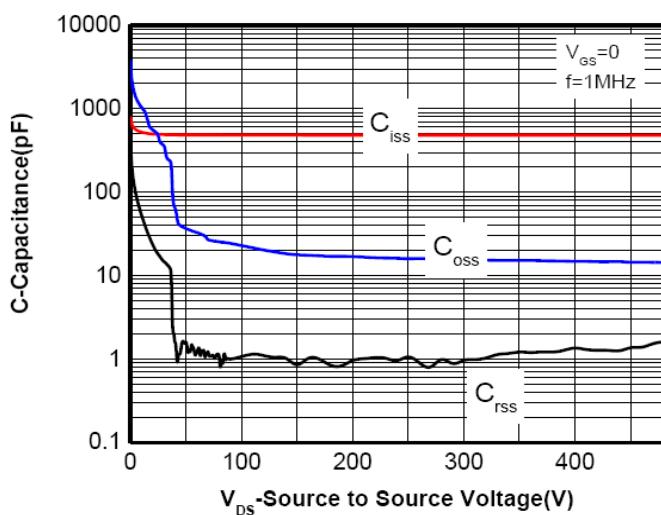
Typ. drain-source on-state resistance



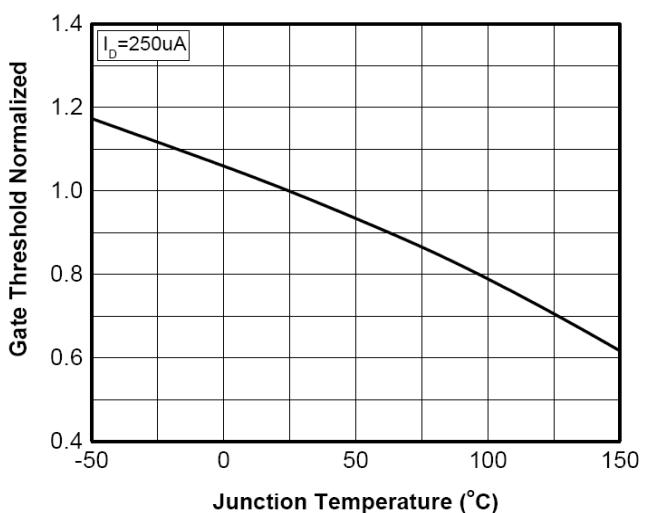
Typ. gate charge characteristics



Typ. capacitances

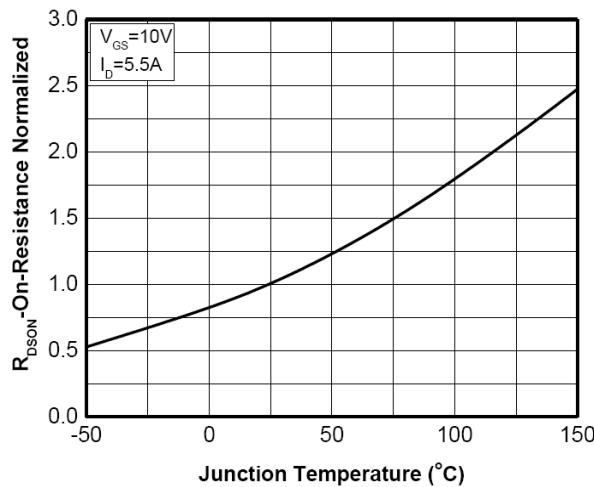


Normalized $V_{GS(th)}$ characteristics

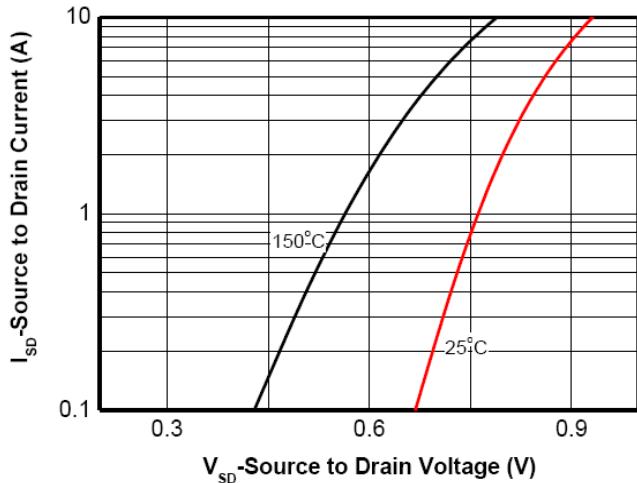


650V Super Junction Power MOSFET

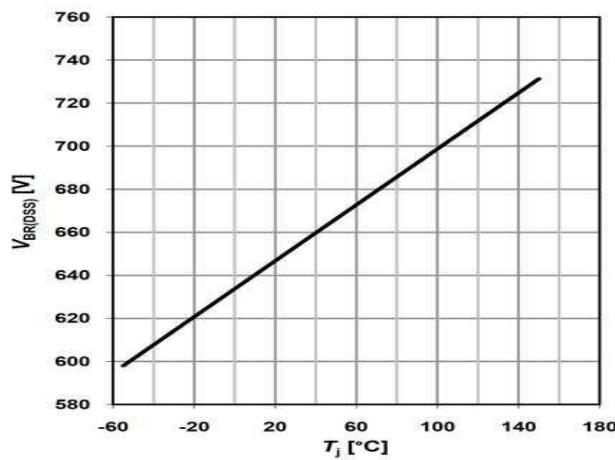
Normalized on-resistance vs temperature



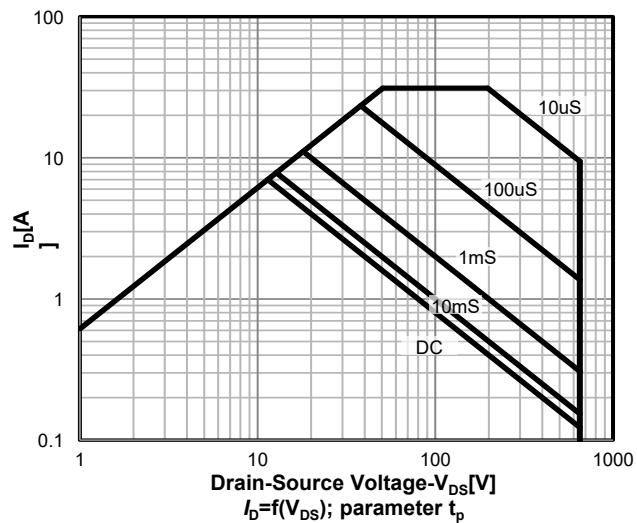
Forward characteristics of reverse diode



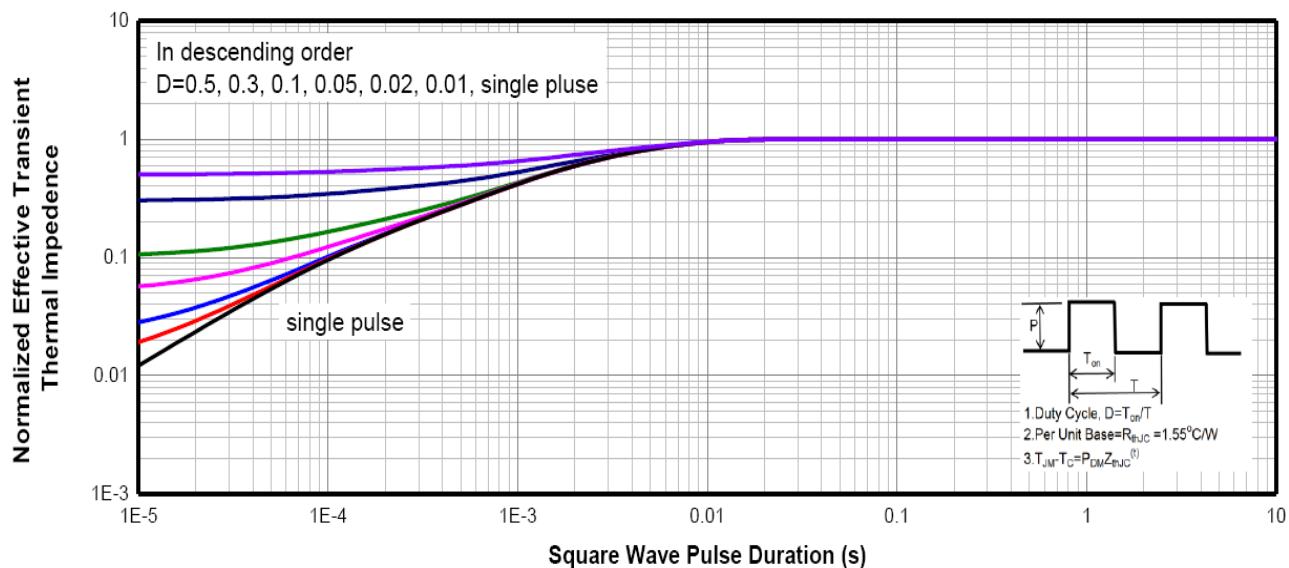
Drain-source breakdown voltage



Safe operating area $TC=25^\circ C$

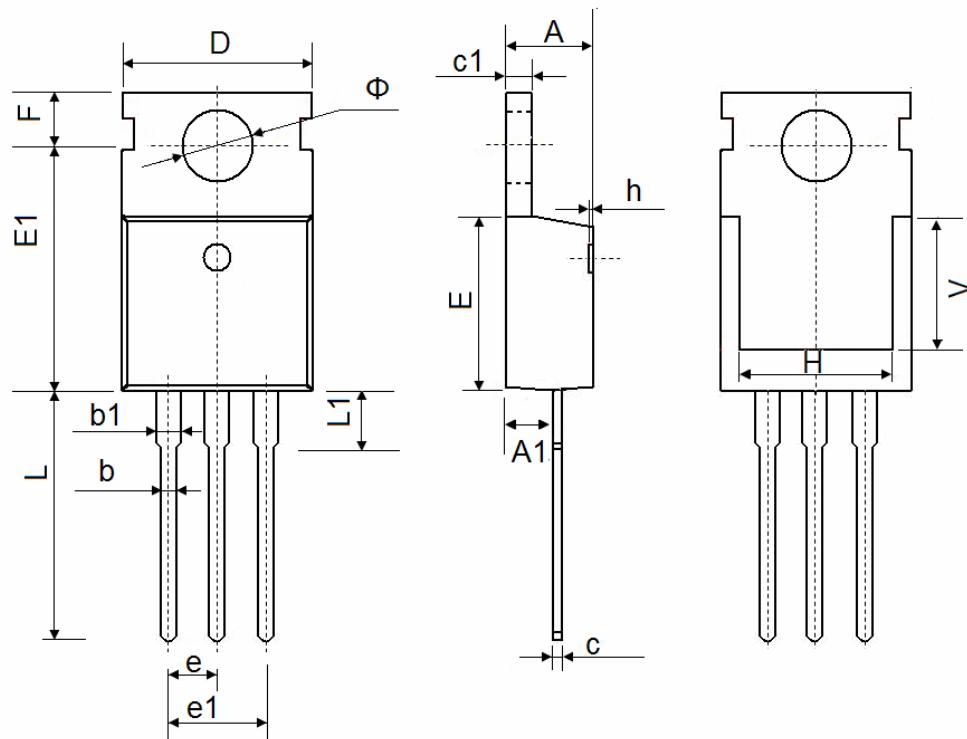


Max. transient thermal impedance



650V Super Junction Power MOSFET

TO-220 Package Outline Data



Symbol	Dimensions In Millimeters	
	Min.	Max.
A	4.350	4.650
A1	2.250	2.550
b	0.710	0.910
b1	1.170	1.400
c	0.330	0.650
c1	1.200	1.400
D	9.910	10.250
E	8.9500	9.750
E1	12.650	12.950
e	2.540 TYP.	
e1	4.980	5.180
F	2.650	2.950
H	7.900	8.100
h	0.000	0.300
L	12.700	13.500
L1	2.850	3.250
V	7.500 REF.	
Φ	3.400	3.800